



Material Content Data Sheet



Sales Product Name		TLE4278G		Issued		20. July 2018		
MA#		MA000970674						
Package		PG-DSO-14-30		Weight*		143.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.312	2.31	2.31	23117	23117
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8423	
wire	non noble metal	copper	7440-50-8	49.007	34.20	35.09	342022	350971
	noble metal	gold	7440-57-5	0.281	0.20	0.20	1960	1960
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1195
encapsulation	plastics	epoxy resin	-	7.879	5.50		54990	
	inorganic material	silicondioxide	60676-86-0	77.594	54.15	59.77	541533	597718
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8557	8557
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7187	7187
glue	plastics	acrylic resin	-	0.331	0.23		2308	
	noble metal	silver	7440-22-4	1.172	0.82	1.05	8182	10490
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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